

Specification of Thermoelectric Module

TEFC1-01712

Description

The 17 couples, 6.2 mm × 6.2 mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

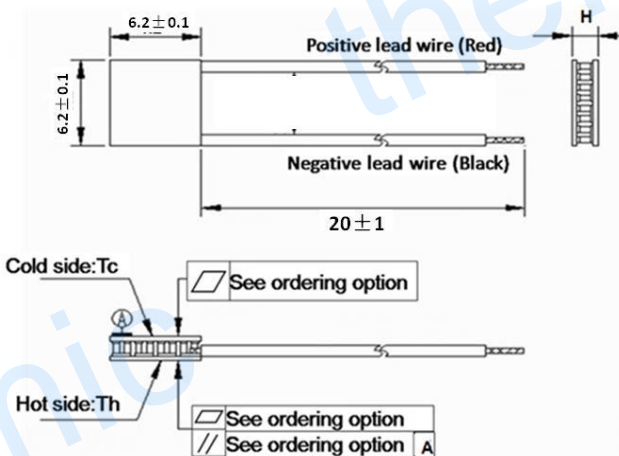
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	2.16	2.35	Voltage applied to the module at DT _{max}
I _{max} (amps)	1.47	1.47	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	1.96	2.11	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.11	1.22	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:2.3±0.1	0:0.015/0.015	20±1/Specify
TF	1:2.3±0.05	1:0.01/0.01	20±1/Specify
TF	2:2.3±0.025	2:0.008/0.008	20±1/Specify

Eg. TF11: Thickness 2.3± 0.05 (mm) and Flatness 0.01 / 0.01 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (T_{mel}=138°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing other than above

C. Ceramics:

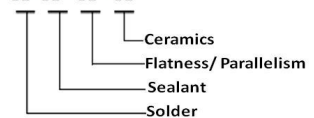
1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metallized)
2. Metallized (Au plating)

Naming for the Module

TEFC1- 01712- X-X-X-X



TEFC1- 01712-T100-NS -TF11 -AIO

T100: BiSn (T_{mel}=138°C)

NS: No sealing

AIO: Alumina, white 96%

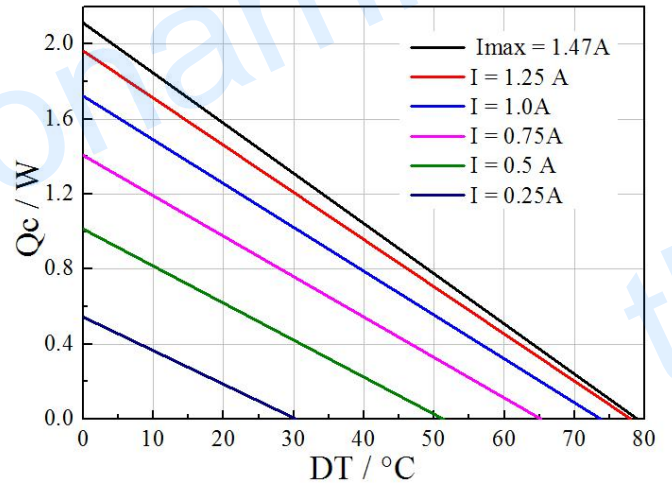
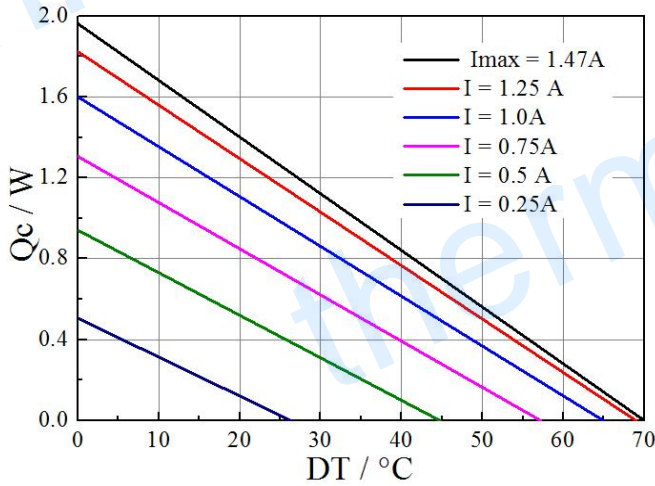
TF11: Thickness ± 0.05 (mm) and Flatness/ Parallelism 0.01/0.01 (mm)

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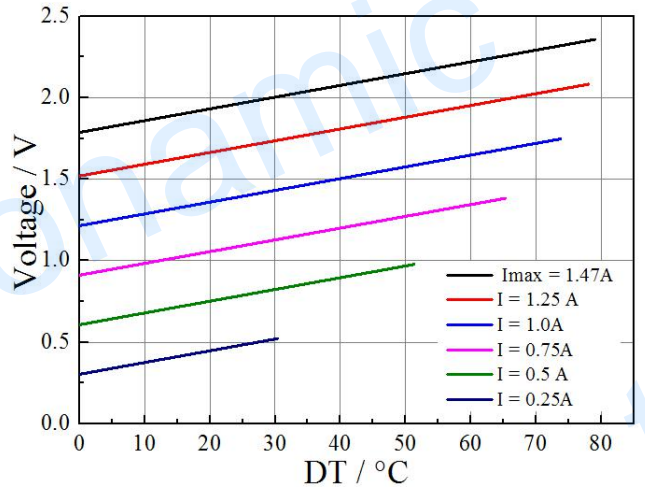
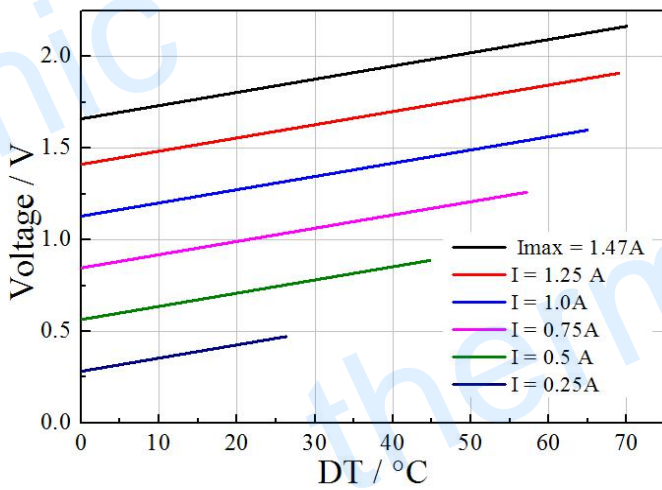
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Performance Curves at Th=27 °C

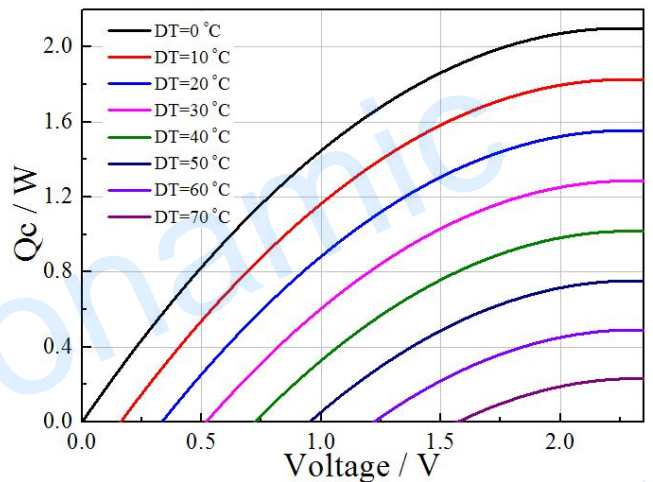
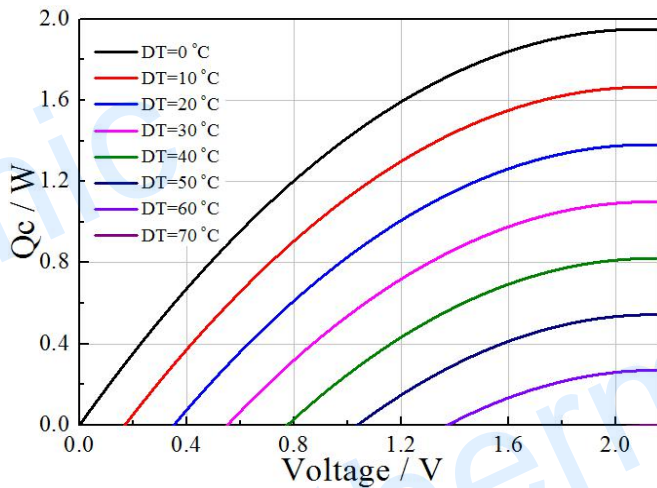
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

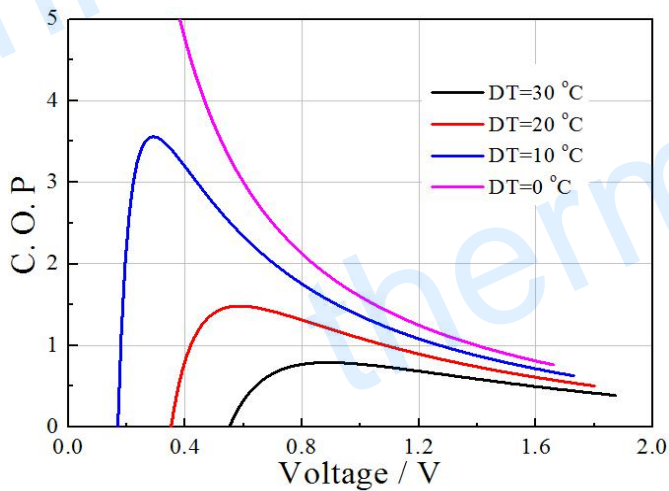


Standard Performance Graph $Q_c = f(V)$

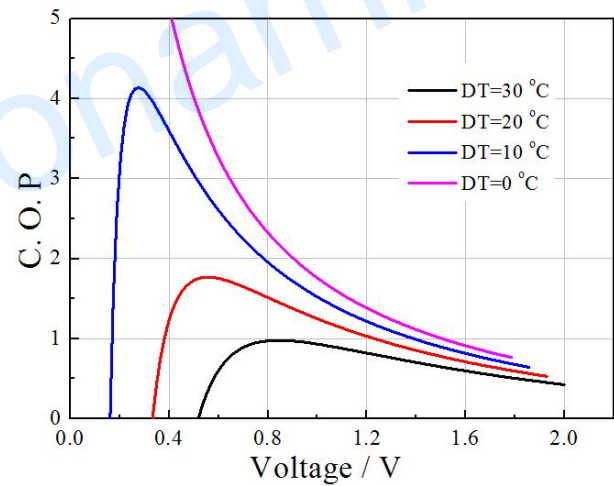
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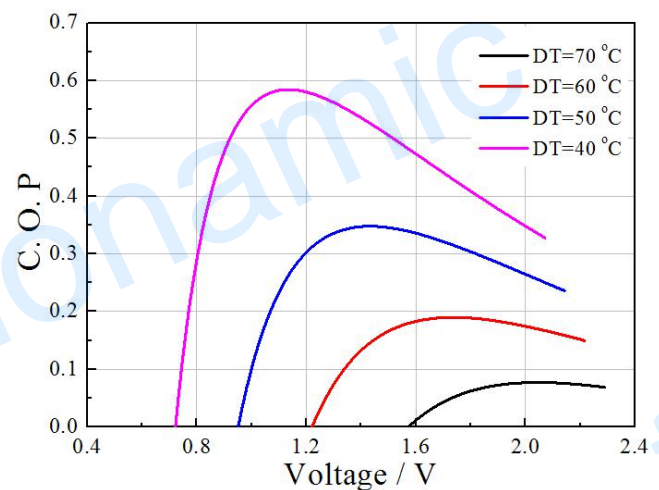
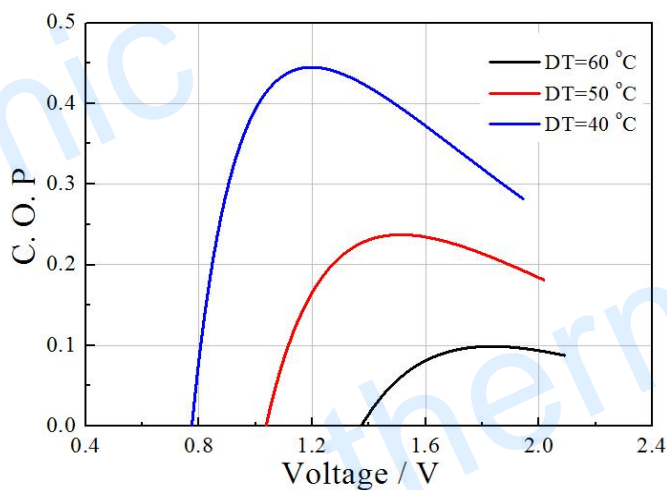
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.